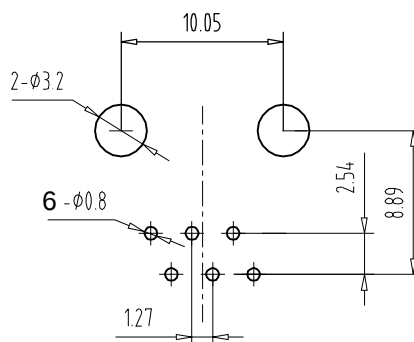
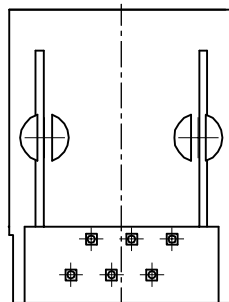
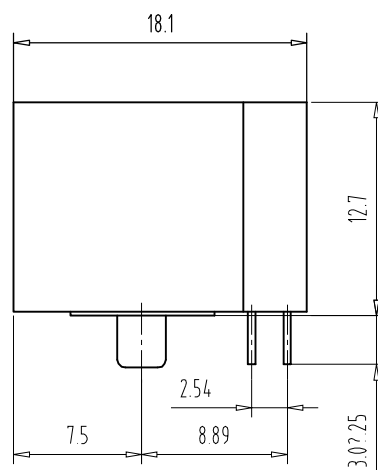
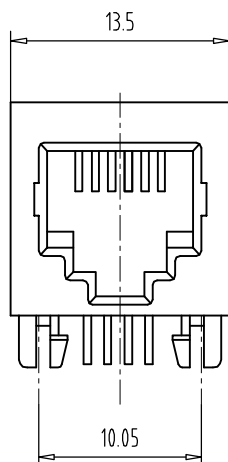




PC Board Layout
Component Side Shown

NOTES:

MATERIAL :

- | | |
|--------------------|---|
| 1.HOUSING MATERIAL | :GLASS FILLED POLYESTER UL94V-0. |
| 2.CONTACT MATERIAL | :PHOSPHOR BRONZE $\phi 0.45\text{mm}$. |
| 3.PLATING | :GOLD PLATING OVER NICKEL. |

ELECTRICAL:

- | | |
|--------------------------------------|------------------------------|
| 1.VOLTAGE RATING | :125 VAC RMS. |
| 2.CURRENT RATING | :1.5 AMP. |
| 3.CONTACT RESISTANCE | :30 MILLIOHMS MAX. |
| 4.INSULATION RESISTANCE | :500 MEGOHMS MIN @ 500V DC . |
| 5.DIELECTRIC WITHSTANDING RESISTANCE | :1000V AC RMS 50Hz. 1MIN. |

MECHANICAL:

- | | |
|----------------------------|------------------|
| 1.DURRABILITY | :750 CYCLES MIN. |
| 2.PCB RETENTION PRE-SOLDER | :1 LB MIN. |

ENVIRONMENTAL:

- | | |
|--------------|---------------|
| 1. STORAGE | : -40°C~+85°C |
| 2. OPERATION | : 0? TO 70?. |



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5" UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ11 90 ° DIP 6P6C全塑	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW38-RJ11-181B
	APPROVED BY: 柯南	DATE : 2014-02-23	DRAW NO:	HYC-RJ19082010
			SHEET NO.	1 OF 1